PC3H2/PC3Q62

# PC3H2/PC3Q62

#### ■ Features

SHARP

- Half pitch surface mount type for high density mounting (Lead pitch: 1.27 mm)
- 2. High resistance to noise due to high common mode rejection voltage (CMR : MIN.10kV/ $\mu$ s)
- 3. Soldering reflow type (230°C, for 30seconds)
- 4. High temperature tested model
- 5. Taping package

PC3H2 (1ch)

PC3Q62 (4ch)

6. Recognized by UL, file No. E64380

## ■ Applications

1. Programmable controllers

Parameter

### **■** Package Specifications

■ Absolute Maximum Ratings

Model No.	Package specification
PC3H2	Taping reel diameter 330mm (3 000pcs)
PC3Q62	Taping reel diameter 330mm (1 000pcs)

Symbol

Rating

1 drumeter		Dymoor	rtuting	Cint	
	*1Forward current	IF	50	mA	
	*2 Peak forward current	Iғм	1	A	
Input	Reverse voltage	VR	6	V	
	*1 Power dissipation	P	70	mW	
-	*1Collector-emitter voltage	Vceo	70	V	
	Emitter-collector voltage	VECO	6	V	
Output	Collector current	Ic	50	mA	
	*1 Collector dissipation	Pc	150	mW	
*1 Total power dissipation		Ptot	170	mW	
Operating temperature		Topr	-30 to +100	°C	

 $T_{stg}$ 

 $V_{iso}$ 

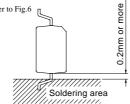
Tsol

Tstg Storage temperature

\*3 Viso Isolation voltage

\*4 Soldering temperature

\*4 For 10s



-40 to +125

2.5

260

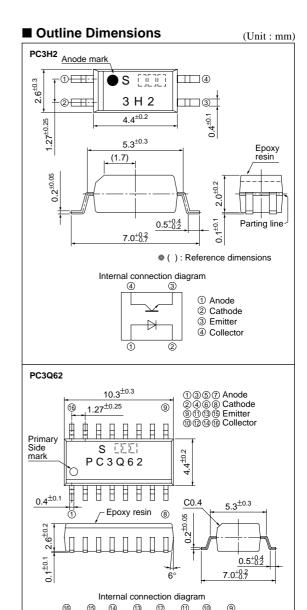
 $(Ta=25^{\circ}C)$ 

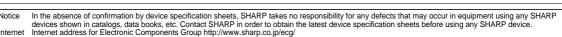
°C

 $kV_{rms}$ 

°C

# High Resistance to Noise, Half Pitch Photocoupler





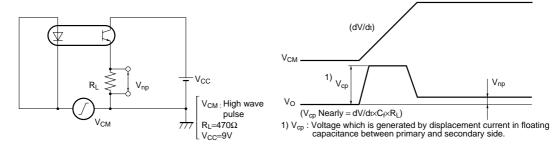
<sup>\*1</sup> The derating factors of absolute maximum ratings due to ambient temperature are shown in Fig.2 to 5

<sup>\*2</sup> Pulse width<=100µs, Duty ratio:0.01, Refer to Fig.6 \*3 AC for 1min., 40 to 60% RH, f=60Hz

■ Electro-optical Characteristics (Ta=25°C)										
Parameter			Symbol	Conditions	MIN.	TYP.	MAX.	Unit		
	Forward voltage		VF	I <sub>F</sub> =20mA	_	1.2	1.4	V		
Input	Reverse current		IR	V <sub>R</sub> =4V	-	-	10	μA		
	Terminal capacitance		Ct	V=0, f=1kHz	_	30	250	pF		
Output	PC3H2		_	V <sub>CE</sub> =50V, I <sub>F</sub> =0			100			
	Collector dark curren	PC3Q62	Iceo	Vce=20V, If=0	1 -	_	100	nA		
	Collector-emitter breakdown voltage		BVCEO	Ic=0.1mA I <sub>F</sub> =0	70	_	_	V		
	Emitter-collector breakdown voltage		BVECO	Iε=10μA, Iε=0	6	_	_	V		
Transfer characteristics	Collector current		Ic	I=1mA Vc=5V	0.2	_	4.0	mA		
	Collector-emitter saturation voltage		V <sub>CE(sat)</sub>	I=20mA Ic=1mA	_	0.1	0.2	V		
	Isolation resistance		Riso	DC500V 40 to 60%RH	5×10 <sup>10</sup>	1×10 <sup>11</sup>	_	Ω		
	Floating capacitance		Cf	V=0, f=1MHz	_	0.6	1.0	pF		
	Response time	Rise time	tr	V <sub>CE</sub> =2V I <sub>C</sub> =2mA	_	4	18	μs		
		Fall time	tf	$R_{L}=100\Omega$	_	3	18	μs		
	*5 Common mode rejection voltage		CMR	Ta=25°C, R <sub>L</sub> =470Ω V <sub>CM</sub> =1.5kV(peak) I <sub>F</sub> =0mA,V <sub>CC</sub> =9V, Vnp=100mV	10	_	_	kV/μs		

<sup>\*5</sup> Refer to Fig.1

Fig.1 Test Circuit for Common Mode Rejection Voltage



SHARP PC3H2/PC3Q62

Fig.2 Forward Current vs. Ambient Temperature

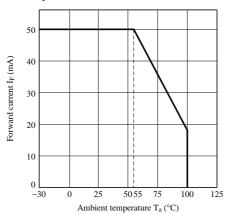


Fig.4 Collector Power Dissipation vs.

Ambient Temperature

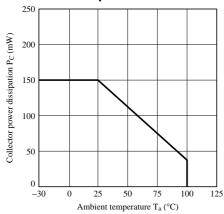


Fig.6 Peak Forward Current vs. Duty Ratio

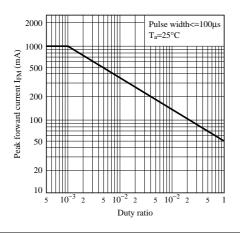


Fig.3 Diode Power Dissipation vs. Ambient Temperature

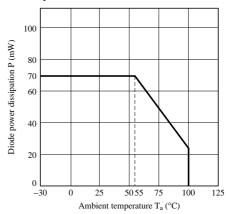


Fig.5 Total Power Dissipation vs. Ambient Temperature

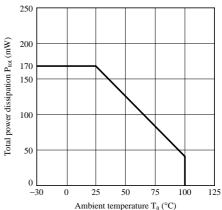
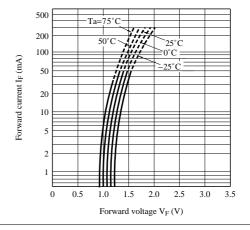


Fig.7 Forward Current vs. Forward Voltage



PC3H2/PC3Q62

Fig.8 Current Transfer Ratio vs. Forward Current

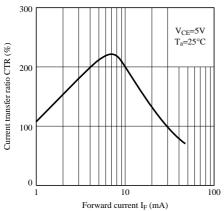


Fig.10 Relative Current Transfer Ratio vs.
Ambient Temperature

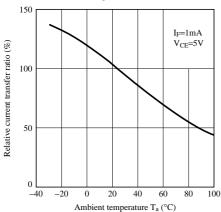


Fig.12 Collector Dark Current vs. Ambient Temperature

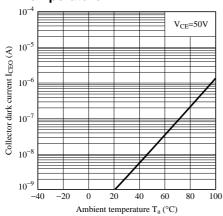


Fig.9 Collector Current vs. Collector-emitter Voltage

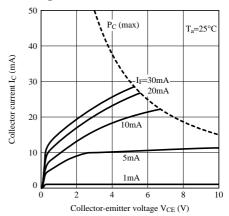


Fig.11 Collector-emitter Saturation Voltage vs. Ambient Temperature

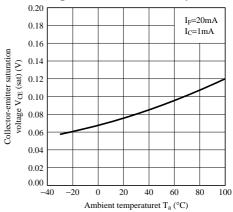
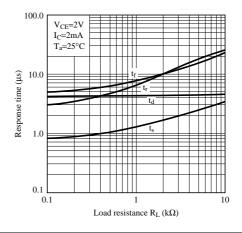


Fig.13 Response Time vs. Load Resistance



SHARP PC3H2/PC3Q62

Fig.14 Test Circuit for Response Time

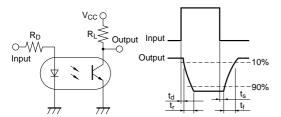


Fig.15 Voltage Gain vs Frequency

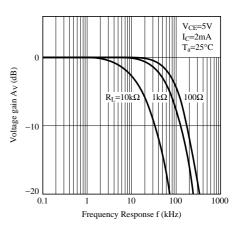


Fig.16 Collector-emitter Saturation Voltage vs. Forward Current

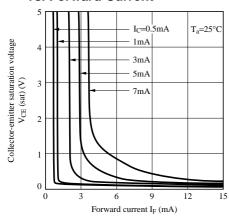
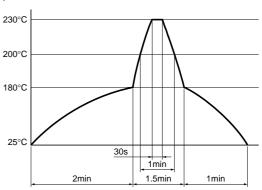


Fig.17 Reflow Soldering

Only one time soldering is recommended within the temperature profile shown below.



#### **NOTICE**

- •The circuit application examples in this publication are provided to explain representative applications of SHARP devices and are not intended to guarantee any circuit design or license any intellectual property rights. SHARP takes no responsibility for any problems related to any intellectual property right of a third party resulting from the use of SHARP's devices.
- •Contact SHARP in order to obtain the latest device specification sheets before using any SHARP device. SHARP reserves the right to make changes in the specifications, characteristics, data, materials, structure, and other contents described herein at any time without notice in order to improve design or reliability. Manufacturing locations are also subject to change without notice.
- Observe the following points when using any devices in this publication. SHARP takes no responsibility for damage caused by improper use of the devices which does not meet the conditions and absolute maximum ratings to be used specified in the relevant specification sheet nor meet the following conditions:
  - (i) The devices in this publication are designed for use in general electronic equipment designs such as:
  - Personal computers
  - Office automation equipment
  - Telecommunication equipment [terminal]
  - Test and measurement equipment
  - Industrial control
  - Audio visual equipment
  - Consumer electronics
  - (ii) Measures such as fail-safe function and redundant design should be taken to ensure reliability and safety when SHARP devices are used for or in connection with equipment that requires higher reliability such as:
  - Transportation control and safety equipment (i.e., aircraft, trains, automobiles, etc.)
  - Traffic signals
  - Gas leakage sensor breakers
  - Alarm equipment
  - Various safety devices, etc.
  - (iii) SHARP devices shall not be used for or in connection with equipment that requires an extremely high level of reliability and safety such as:
  - Space applications
  - Telecommunication equipment [trunk lines]
  - Nuclear power control equipment
  - Medical and other life support equipment (e.g., scuba).
- •Contact a SHARP representative in advance when intending to use SHARP devices for any "specific" applications other than those recommended by SHARP or when it is unclear which category mentioned above controls the intended use.
- •If the SHARP devices listed in this publication fall within the scope of strategic products described in the Foreign Exchange and Foreign Trade Control Law of Japan, it is necessary to obtain approval to export such SHARP devices.
- •This publication is the proprietary product of SHARP and is copyrighted, with all rights reserved. Under the copyright laws, no part of this publication may be reproduced or transmitted in any form or by any means, electronic or mechanical, for any purpose, in whole or in part, without the express written permission of SHARP. Express written permission is also required before any use of this publication may be made by a third party.
- Contact and consult with a SHARP representative if there are any questions about the contents of this
  publication.